



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	28-10-2023
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	Representative Title	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32MP135AAG3	284M*501XXXY	A	9991	28-10-2023
	Amount	UoM	Unit type	ST ECOPACK Grade
	500.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	NAC	Copper Alloy	SACN305	

Package Designator	Size	Nbr of instances	Shape	
BGA	9x9	289	bulk solder	
Comment	Package : B0EB TFBGA 9X9 289L PITCH 0.5 MM DM00699787			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-14th June 2023				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	284M*501XXY				6000002.0	1000000.0								
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)								
Die or dies	M-011 Other inorganic materials	7.220	mg	supplier	die	Silicon (Si)	7440-21-3		6.700	mg	927978	13400								
				supplier	metallization	Aluminium (Al)	7429-90-5		0.058	mg	8033	116								
				supplier	metallization	Copper (Cu)	7440-50-8		0.171	mg	23684	342								
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	139	2								
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.029	mg	4017	58								
				supplier	metallization	Titanium (Ti)	7440-32-6		0.007	mg	970	14								
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	139	2								
				supplier	Passivation	Silicon Nitride	12033-89-5		0.041	mg	5679	82								
				supplier	Passivation	Silicon Oxide	7631-86-9		0.212	mg	29363	424								
				Substrate (A29368)	M-011 Other inorganic materials	180.145	mg	supplier	BT-substrate	Thermosetting resin (Inorganic filler)	Proprietary		24.590	mg	136500	49180				
supplier	BT-substrate	Glass cloth	65997-17-3						56.926	mg	316000	113852								
supplier	BT-substrate	Copper foil	7440-50-8						75.120	mg	417000	150241								
supplier	Solder mask	2-benzyl-2-dimethylamino-4-morpholinobutyr	119313-12-1						8.197	mg	45500	16393								
supplier	Solder mask	Naphtha (petroleum), heavy aromatic	64742-94-5						8.107	mg	45000	16213								
supplier	Solder mask	TALC (CONTAINING NO ASBESTOS FIBRES)	14807-96-6						6.035	mg	33500	12070								
supplier	Solder mask	1,3,5-Triazine-2,4,6-triamine	108-78-1						1.171	mg	6500	2342								
supplier	film	Copper (Cu)	7440-50-8						3.059	mg	786250	6117								
supplier	film	Silver (Ag)	7440-22-4						0.204	mg	52500	408								
supplier	film	2,2-dimethyl-1,3-propanediyl bismethacrylate	1985-51-9						0.165	mg	42500	331								
DAF (2100AC)	M-011 Other inorganic materials	3.890	mg	supplier	film	A mixture of: 4-allyl-2,6-bis (2,3-epoxypropyl)g	Proprietary		0.219	mg	56205	437								
				supplier	film	2-[[[2,2-bis[[[1-oxoallyloxy]methyl]butoxy]met	94108-97-1		0.152	mg	39195	305								
				supplier	film	tert-butyl peroxyneodecanoate	26748-41-4		0.088	mg	22500	175								
				supplier	film	Hydroquinone	123-31-9		0.003	mg	850	7								
				Bonding wire (Cu)	Precious metals	4.606	mg	supplier	Bonding wire	Copper (Cu)	7440-50-8		4.447	mg	965500	8894				
								supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.143	mg	31000	286				
								supplier	Bonding wire	Gold (Au)	7440-57-5		0.016	mg	3500	32				
								Encapsulation (KE-G1250AAS)	M-011 Other inorganic materials	280.420	mg	supplier	Molding Compound	Silica(Fused)	60676-86-0,7631-86-9		252.378	mg	900000	504756
												supplier	Molding Compound	Epoxy resin	Proprietary		11.217	mg	40000	22434
				supplier	Molding Compound	Phenol resin	Proprietary		15.704	mg	56000	31407								
supplier	Molding Compound	Carbon Black	1333-86-4		1.122	mg	4000	2243												
Solder balls (SACN305)	M-011 Other inorganic materials	23.719	mg	supplier	Matte Sn	Tin (Sn)	7440-31-5		22.877	mg	964500	45754								
				supplier	Matte Sn	Silver(Ag)	7440-22-4		0.712	mg	30000	1423								
				supplier	Matte Sn	Copper (Cu)	7440-50-8		0.119	mg	5000	237								
				supplier	Matte Sn	Nickel (Ni)	7440-02-0		0.012	mg	500	24								